Kingbright

2.0x1.25mm SMD CHIP LED LAMP

Part Number: KPHBM-2012LVSURKZGKC

Hyper Red
Green

ATTENTION
OBSERVE PRECAUTIONS
FOR HANDLING
ELECTROSTATIC
DISCHARGE
SENSITIVE
DEVICES

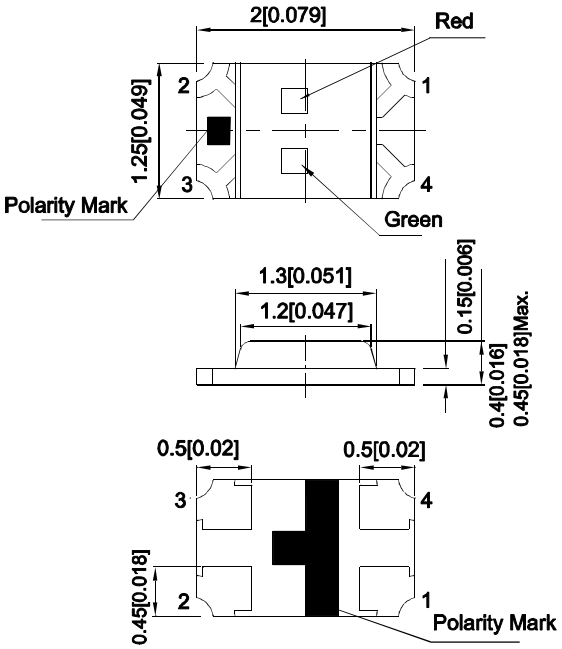
Features

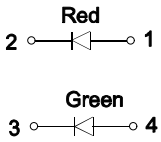
- 2.0mmx1.25mm SMD LED, 0.45mm max. thickness.
- Bi -color, low power consumption.
- Wide viewing angle.
- Ideal for backlight and indicator.
- Package : 2000pcs / reel.
- Moisture sensitivity level : level 3.
- Low current IF=2mA operating.
- RoHS compliant.

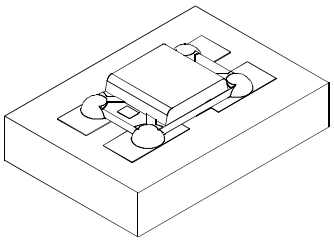
Descriptions

- The Hyper Red source color devices are made with Al GaInP on GaAs substrate Light Emitting Diode.
- The Green source color devices are made with InGaN on Sapphire Light Emitting Diode.
- Electrostatic discharge and power surge could damage the LEDs.
- It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs.
- All devices, equipments and machineries must be electrically grounded.

Package Dimensions







Notes:
1. All dimensions are in millimeters (inches).
2. Tolerance is ±0.1(0.004") unless otherwise noted.
3. The specifications, characteristics and technical data described in the datasheet are subject to change without prior notice.
4. The device has a single mounting surface. The device must be mounted according to the specifications.

Selection Guide

Part No.	Emitting Color (Material)	Lens Type	Iv (mcd) [2] @ 2mA		Viewing Angle [1]
			Min.	Typ.	2θ1/2
KPHBM-2012LVSURKZGKC	Hyper Red (AlGaInP)	Water Clear	10	20	120°
			*2	*10	
	Green (InGaN)		50	90	
			*50	*90	

Notes:
1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 of the optical peak value.
2. Luminous intensity / luminous Flux: +/-15%.
 * Luminous intensity value is traceable to CIE127-2007 standards.

Electrical / Optical Characteristics at TA=25°C

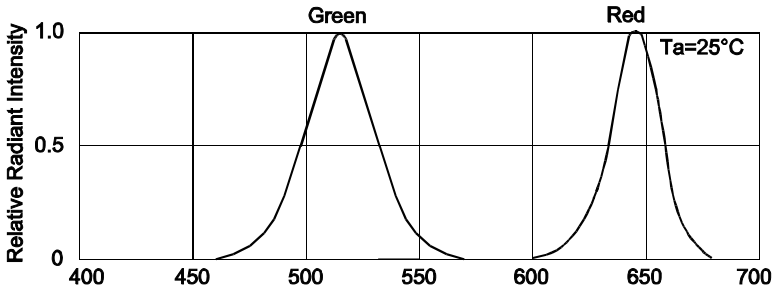
Symbol	Parameter	Emitting Color	Min.	Typ.	Max.	Units	Test Conditions
λpeak	Peak Wavelength	Hyper Red Green		645 515		nm	I_F=2mA
λD [1]	Dominant Wavelength	Hyper Red Green		630 525		nm	I_F=2mA
Δλ1/2	Spectral Line Half-width	Hyper Red Green		28 35		nm	I_F=2mA
C	Capacitance	Hyper Red Green		35 45		pF	V_F=0V;f=1MHz
V_F [2]	Forward Voltage	Hyper Red Green	1.5 2.2	1.75 2.65	2.1 3.1	V	I_F=2mA
I_R	Reverse Current	Hyper Red Green			10 50	uA	V_R = 5V

Notes:
1. Wavelength: +/-1nm.
2. Forward Voltage: +/-0.1V.
3. Wavelength value is traceable to CIE127-2007 standards.
4. Excess driving current and / or operating temperature higher than recommended conditions may result in severe light degradation or premature failure.

Absolute Maximum Ratings at TA=25°C

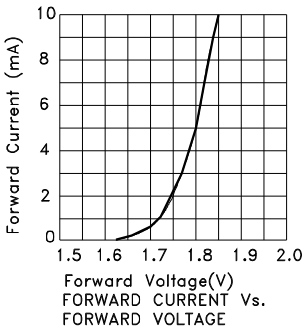
Parameter	Hyper Red	Green	Units
Power dissipation	63	77.5	mW
DC Forward Current	30	25	mA
Peak Forward Current [1]	185	150	mA
Reverse Voltage	5		V
Electrostatic Discharge Threshold (HBM)	3000	450	V
Operating Temperature	-40°C To +85°C		
Storage Temperature	-40°C To +85°C		

Notes:
1. 1/10 Duty Cycle, 0.1ms Pulse Width.
2. Relative humidity levels maintained between 40% and 60% in production area are recommended to avoid the build-up of static electricity – Ref JEDEC/JESD625-A and JEDEC/J-STD-033.

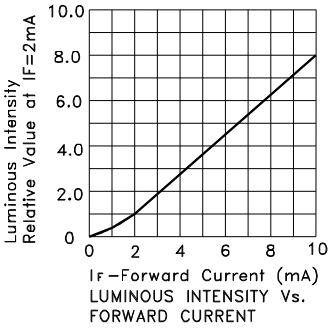


Relative Intensity Vs. Wavelength

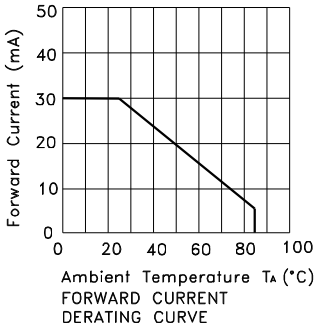
KPHBM-2012LVSURKZGKC
Hyper Red



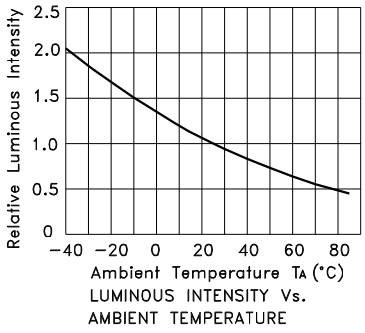
FORWARD CURRENT Vs.
FORWARD VOLTAGE



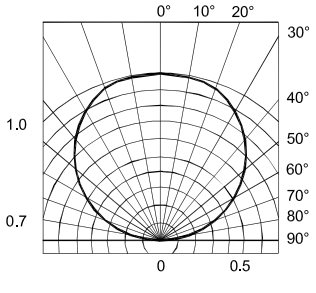
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE

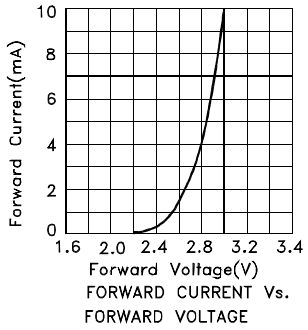


LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

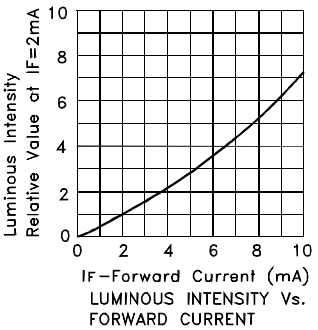


SPATIAL DISTRIBUTION

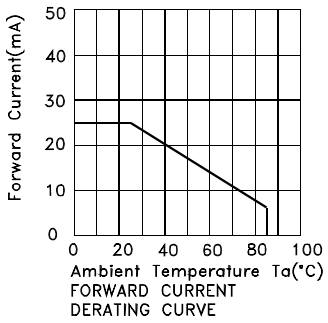
Green



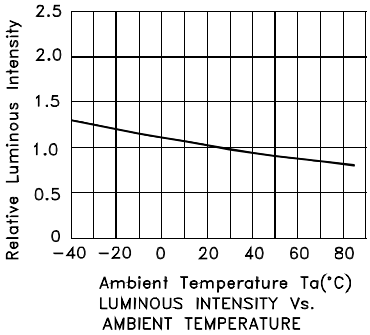
FORWARD CURRENT Vs.
FORWARD VOLTAGE



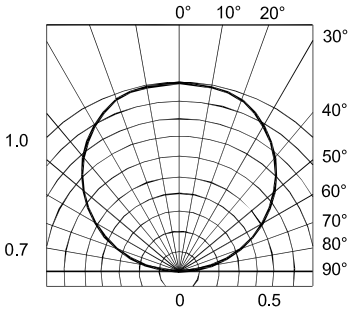
LUMINOUS INTENSITY Vs.
FORWARD CURRENT



FORWARD CURRENT
DERATING CURVE



LUMINOUS INTENSITY Vs.
AMBIENT TEMPERATURE

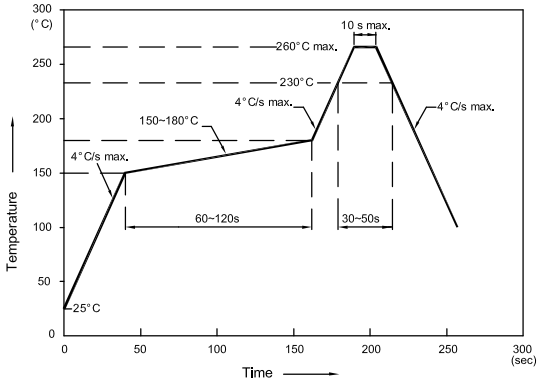


SPATIAL DISTRIBUTION

KPHBM-2012LVSURKZGKC

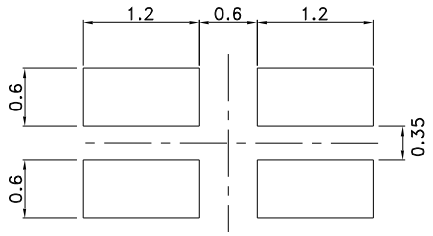
Reflow soldering is recommended and the soldering profile is shown below.
Other soldering methods are not recommended as they might cause damage to the product.

Reflow Soldering Profile For Lead-free SMT Process.

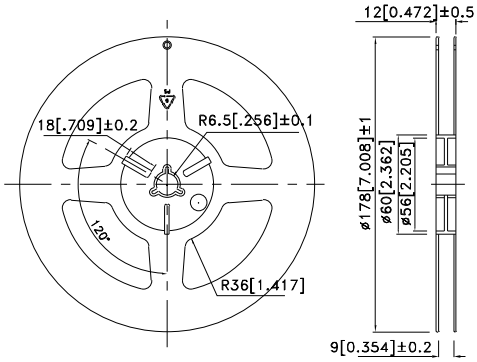


NOTES:
1. We recommend the reflow temperature 245°C(+/-5°C).The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

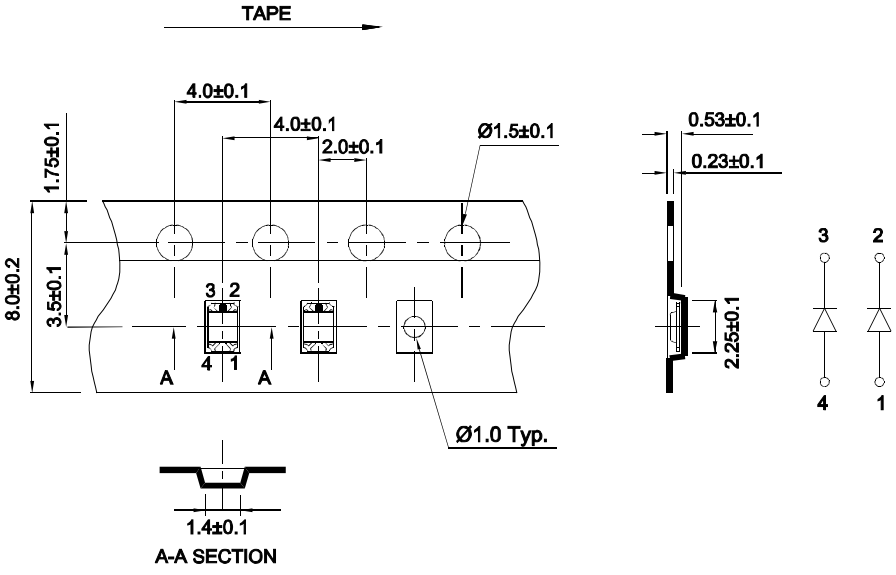
Recommended Soldering Pattern (Units : mm; Tolerance: ± 0.1)



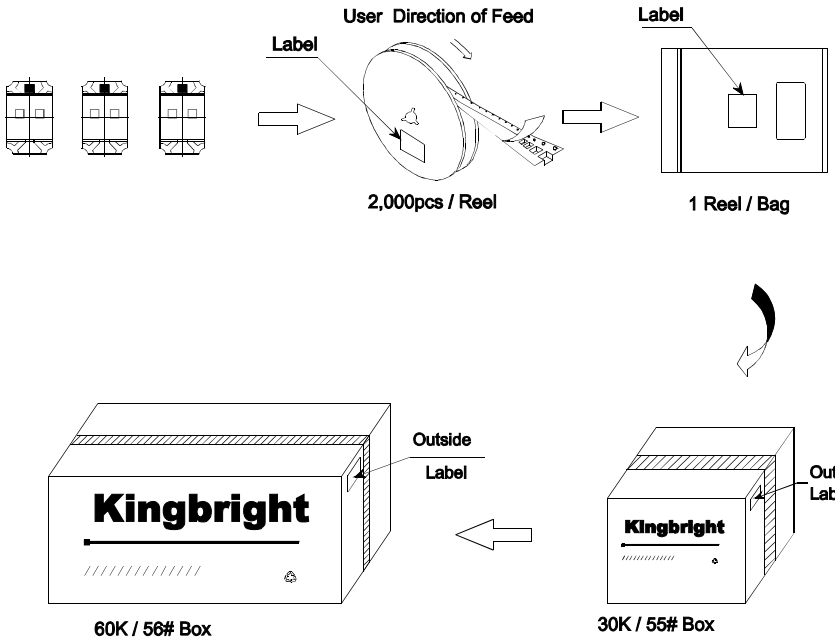
Reel Dimension

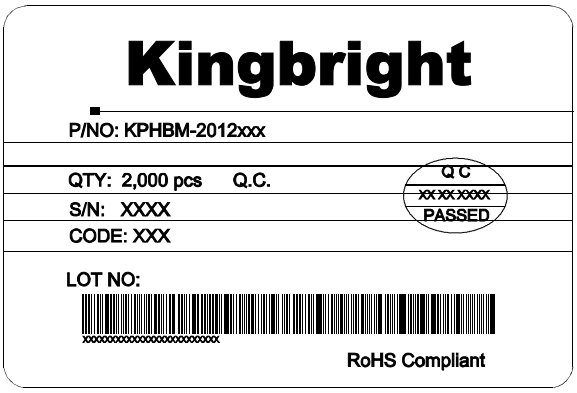


Tape Dimensions (Units : mm)



PACKING & LABEL SPECIFICATIONS **KPHBM-2012LVSURKZGKC**





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